



Chuang-Chieh Lin &lt;josephcclin@gmail.com&gt;

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**[Applied Sciences] Manuscript ID: applsci-1234661 - Revised Version Review Request**

1 message

**Applied Sciences Editorial Office** <applsci@mdpi.com>

Thu, May 27, 2021 at 3:01 PM

Reply-To: Ariel Wang &lt;ariel.wang@mdpi.com&gt;

To: Chuang-Chieh Lin &lt;josephcclin@iis.sinica.edu.tw&gt;

Cc: Applied Sciences Editorial Office &lt;applsci@mdpi.com&gt;, Ariel Wang &lt;ariel.wang@mdpi.com&gt;

Dear Dr. Lin,

You recently kindly reviewed the original version of the following manuscript, submitted to Applied Sciences:

Title: A Reference Mapping Considering Swaps of Adjacent Bases  
Authors: Youngho Kim, Munseong Kang, Ju-Hui Jeong, Dae Woong Kang, Soo Jun Park, Jeong Seop Sim \*

The authors have now provided a revised version along with a cover letter in which they address the referees' comments.

Please let us know, within 3 days, if you believe the manuscript has been sufficiently improved to warrant publication in Applied Sciences. If you need more time to check the revised version, please let the Editorial Office know in advance. Please click on the link below to access the revised manuscript and the review report form:

<https://susy.mdpi.com/user/review/review/18015479/NY9I3tCc>

We look forward to hearing from you soon.

Kind regards,

Ms. Ariel Wang  
E-Mail: [ariel.wang@mdpi.com](mailto:ariel.wang@mdpi.com)

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